

3. Annual MT Meeting



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Flip-Chip Bonding at DESY: Experiences & Outlook

Tuesday 31 January 2017 18:54 (3 minutes)

- Solder Jetting
- Flip-Chip Bonding
- Limits & Flexibilities
- CMS BPix & DTS SiPM

Topic (ARD or DTS)

DTS

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Session Classification: Poster Session